

Title (en)

MODULE FOR A HYBRID CARD

Title (de)

MODUL FÜR EINE HYBRIDKARTE

Title (fr)

MODULE POUR CARTE HYBRIDE

Publication

EP 1588319 A1 20051026 (EN)

Application

EP 04700743 A 20040108

Priority

- IB 2004000015 W 20040108
- EP 03290044 A 20030108
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Abstract (en)

[origin: EP1437684A1] The assembly has a lead frame with two sides in which one side has predefined areas with connection holes (C1- C8) and has a main predefined area with a connection hole (C6). An integrated circuit e.g. radio frequency chip (RFC) is fixed onto the main predefined area. The assembly is embedded in the smart card e.g. integrated circuit card having the geometry of an ISO bank card. Independent claims are also included for the following: (a) an integrated circuit card (b) a communication device.

IPC 1-7

G06K 19/077; H01L 23/498

IPC 8 full level

G06K 19/077 (2006.01); H01L 23/498 (2006.01); H01L 25/065 (2006.01); H05K 1/18 (2006.01)

CPC (source: EP)

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Citation (search report)

See references of WO 2004063980A1

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